

Fig. 1

Fig. 2A

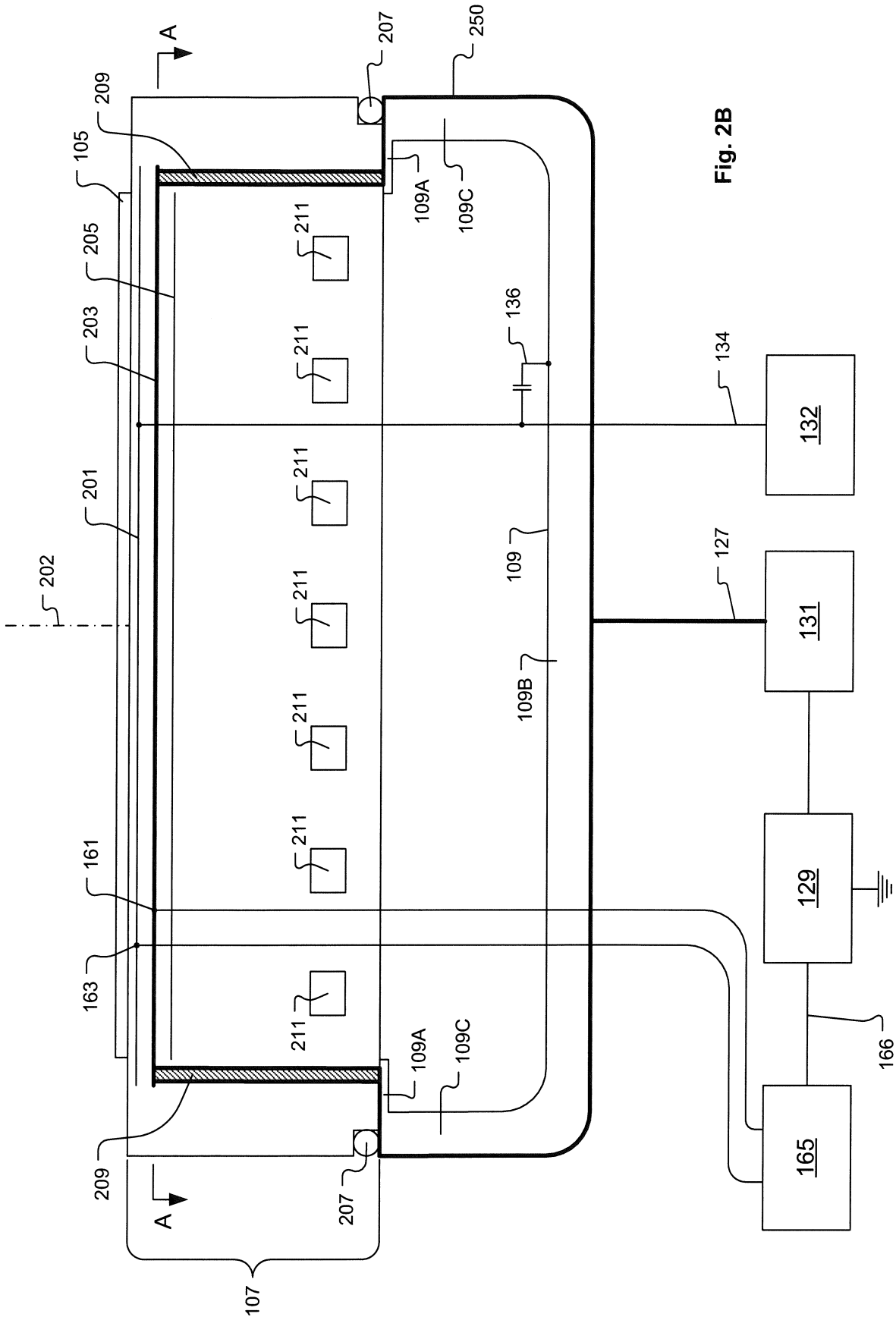
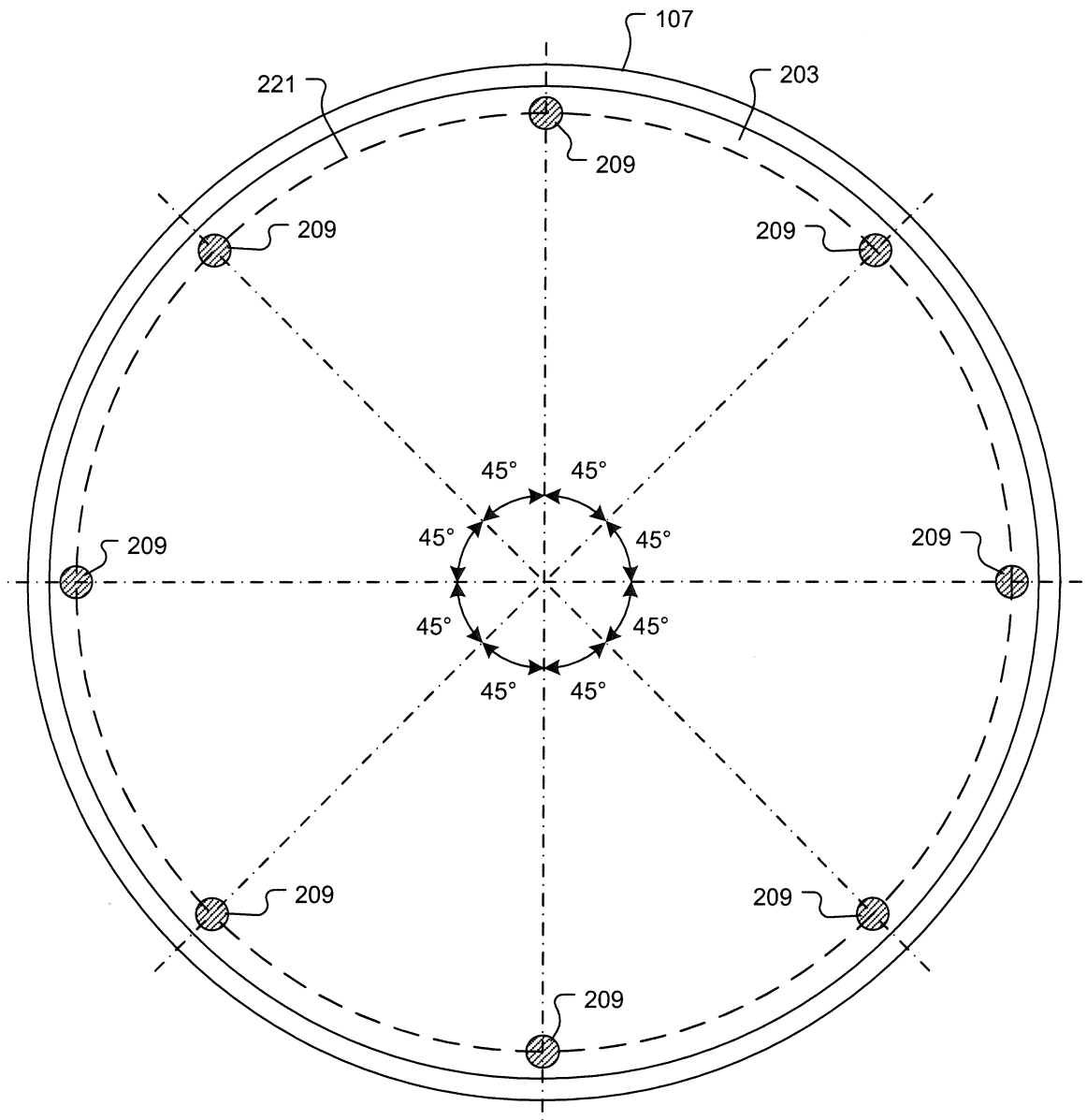
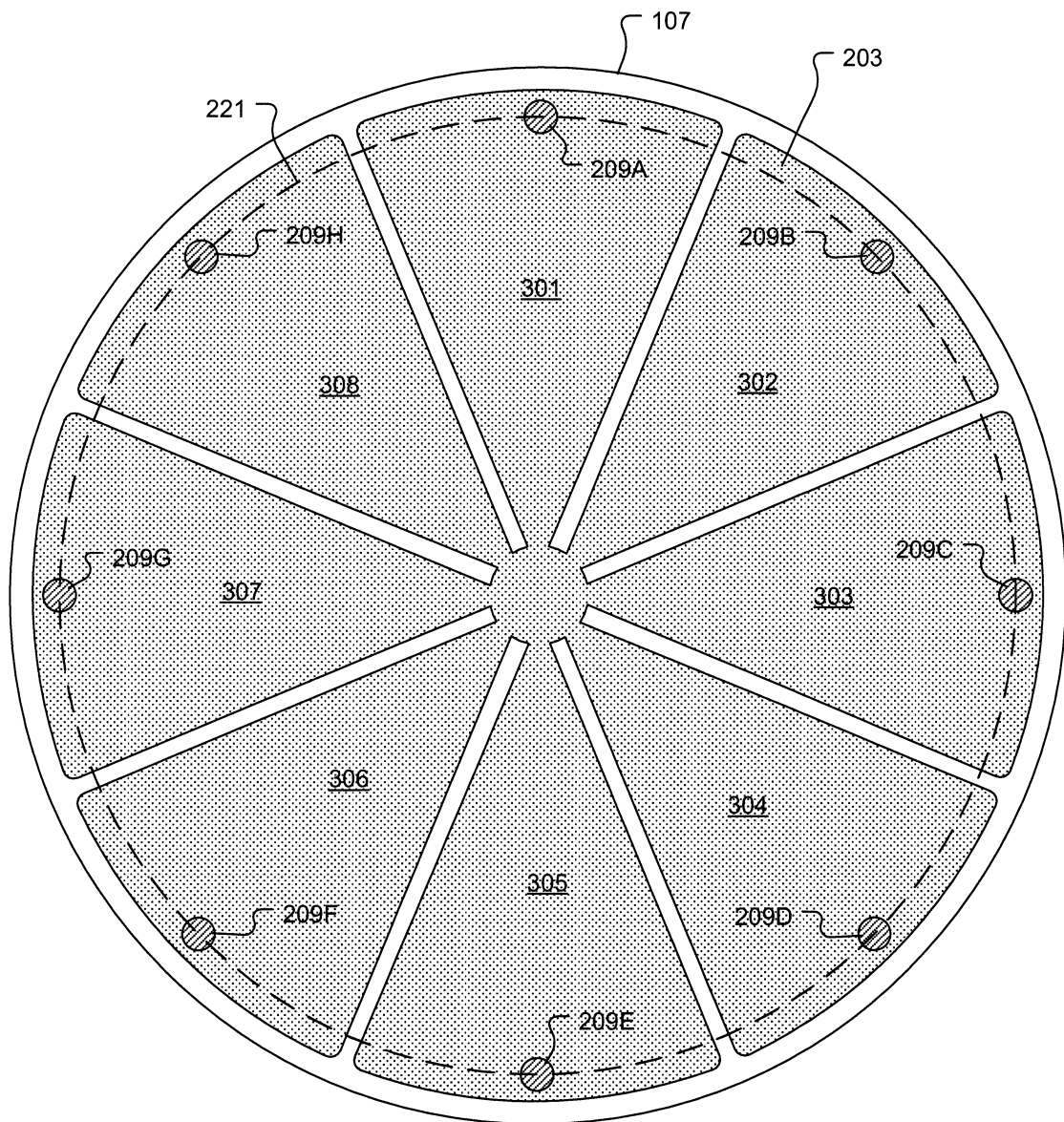


Fig. 2B



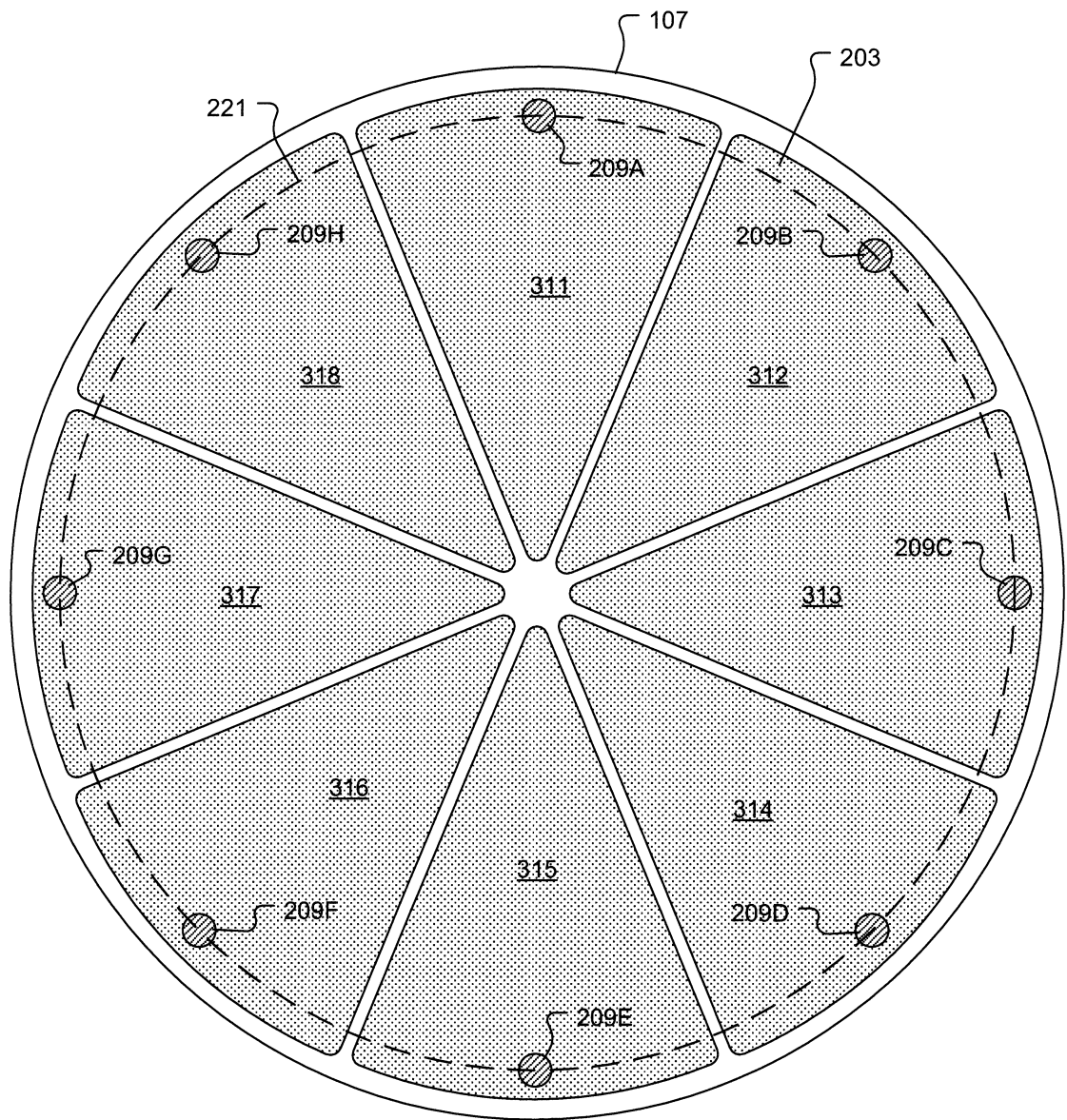
View A-A

Fig. 3A



View A-A

Fig. 3B



View A-A

Fig. 3C

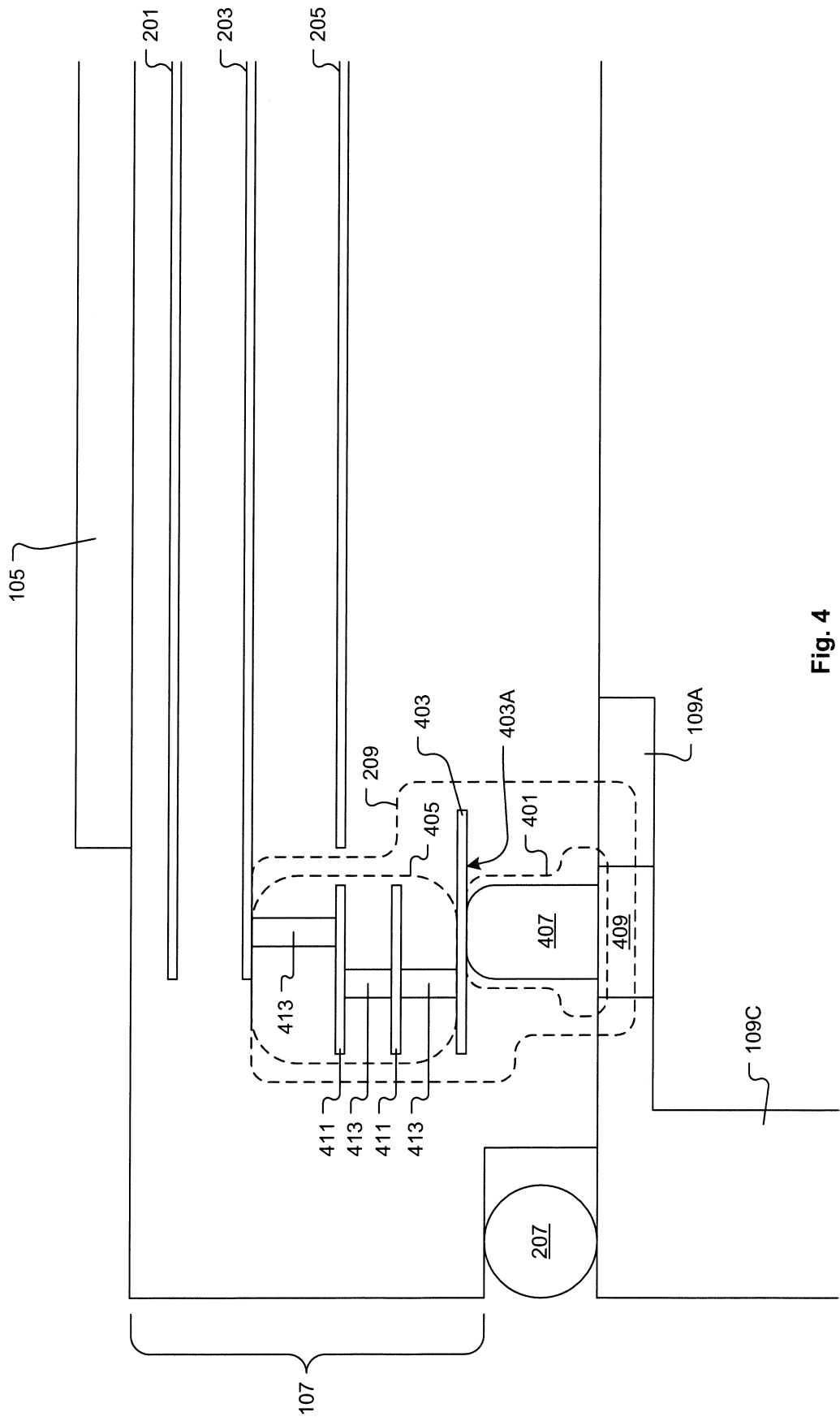


Fig. 4

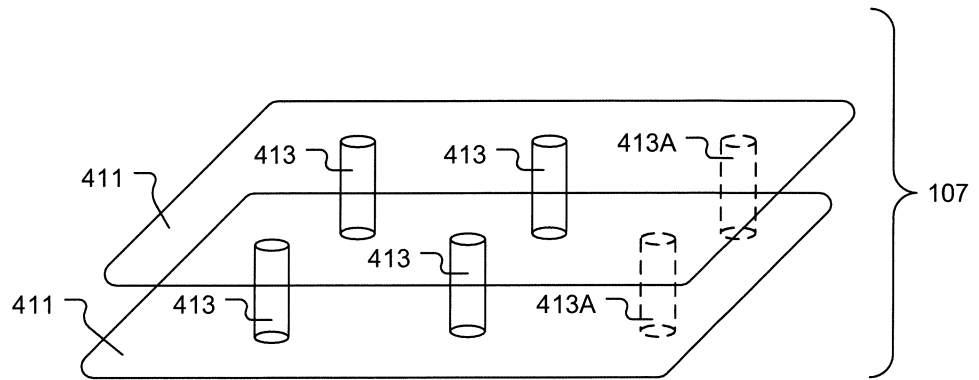


Fig. 5

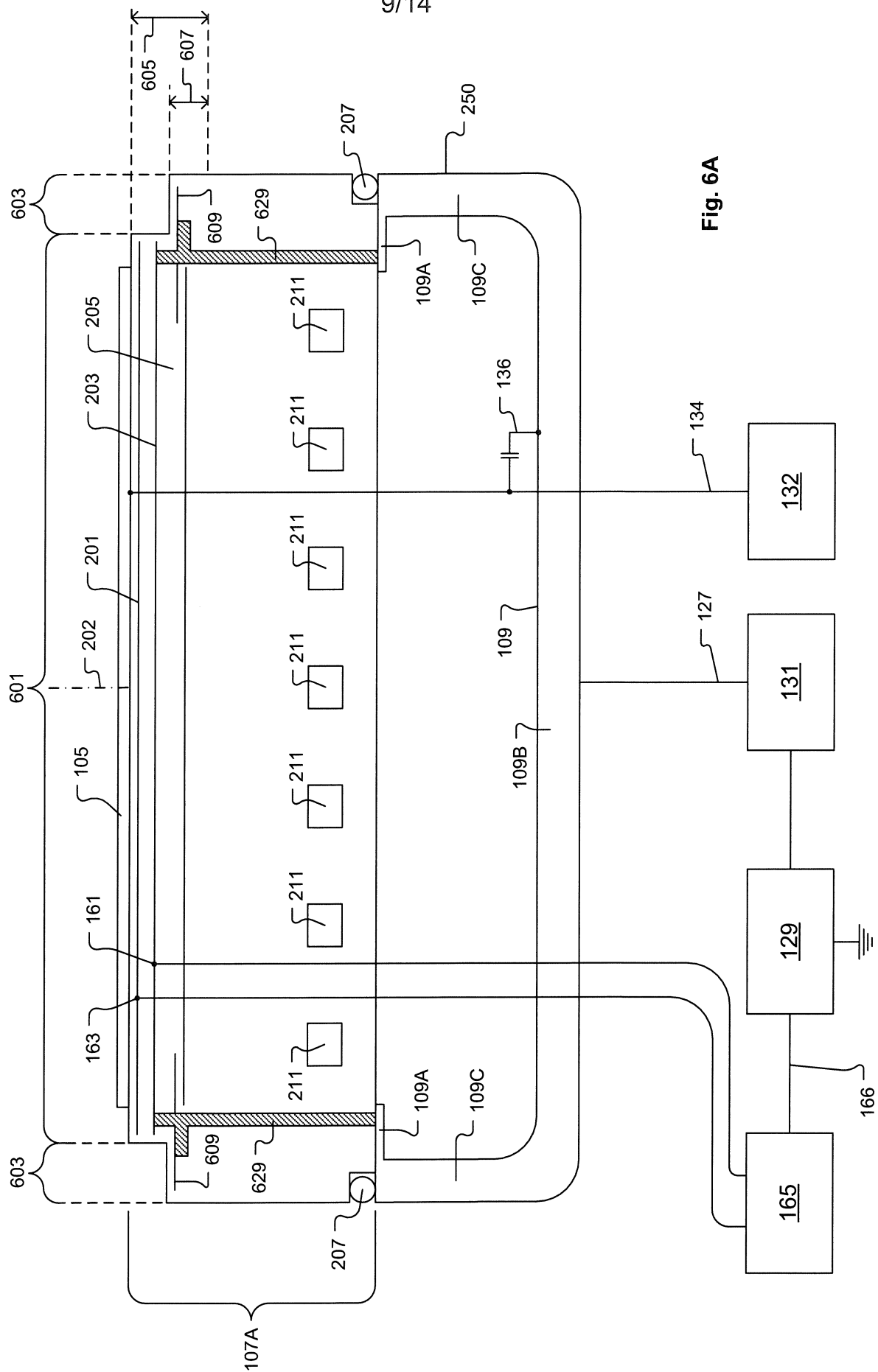


Fig. 6A

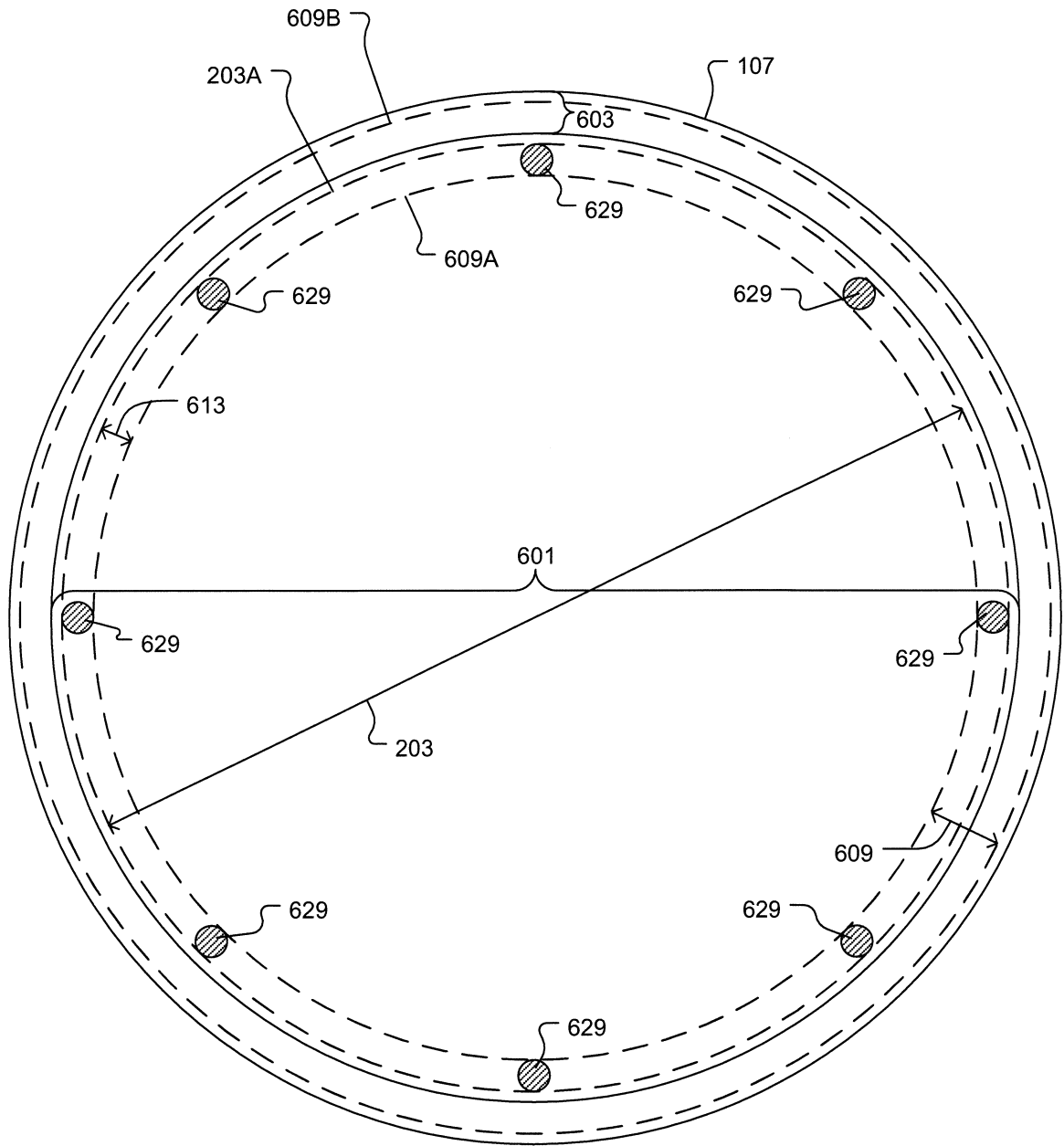


Fig. 6B

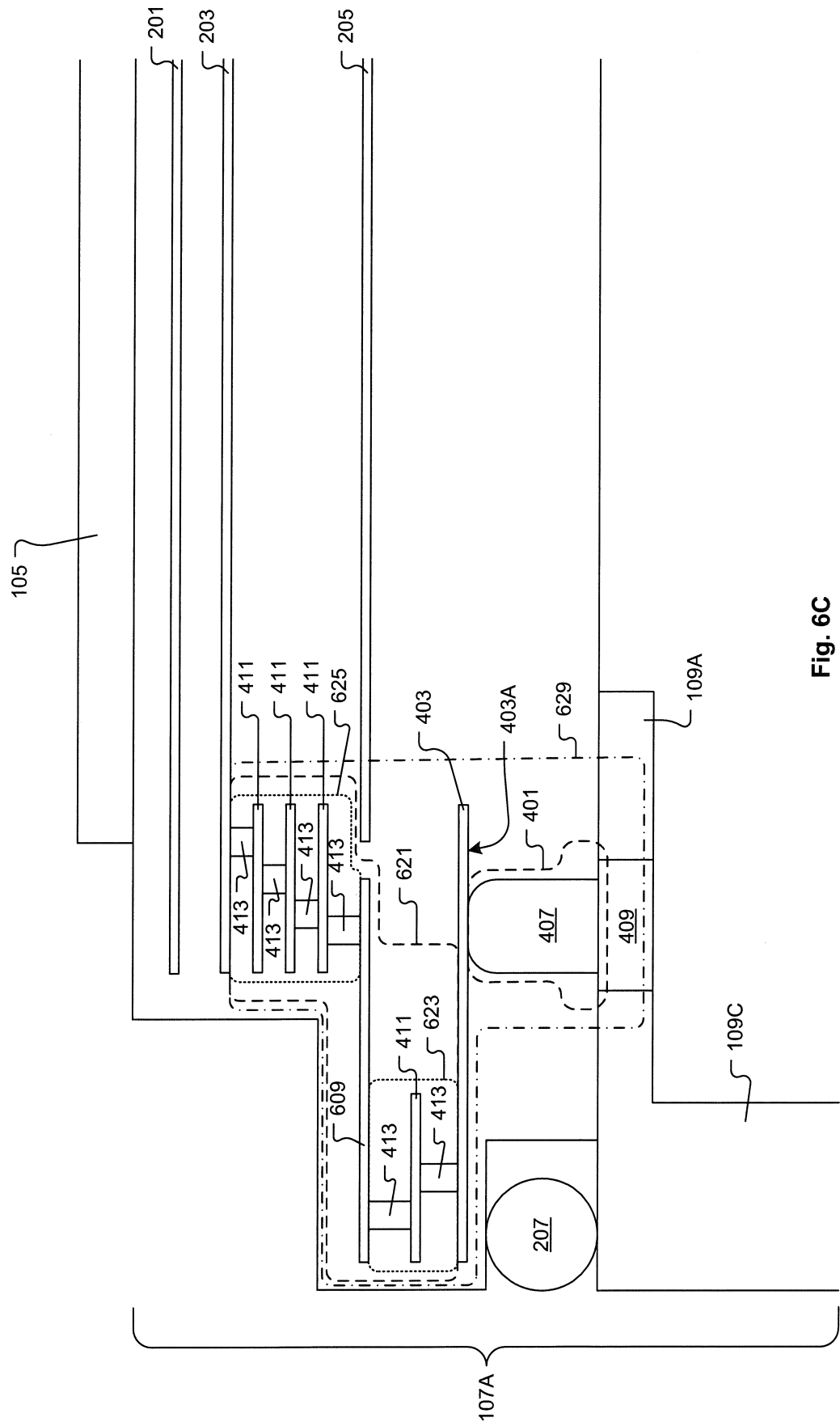


Fig. 6C

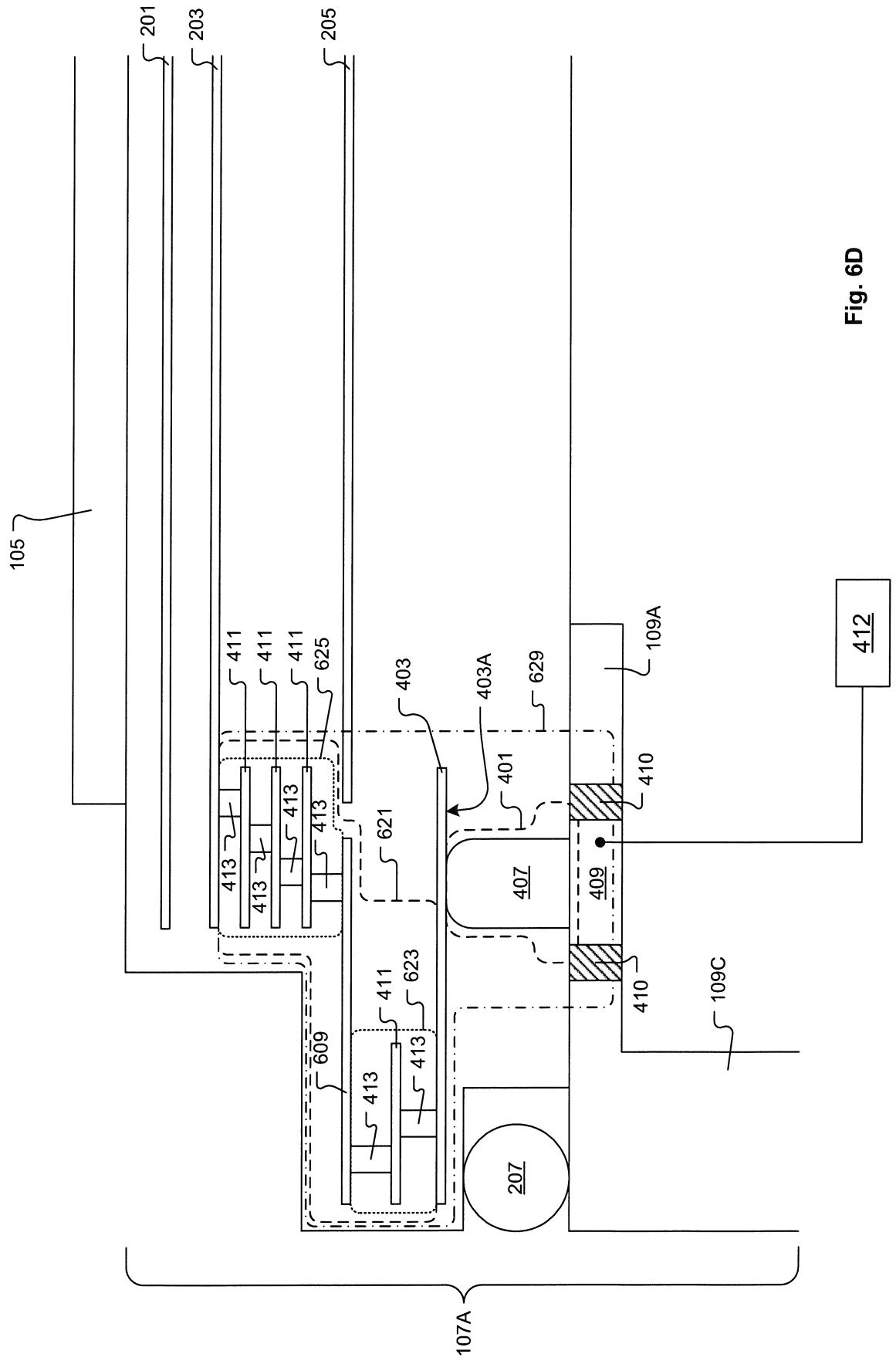


Fig. 6D

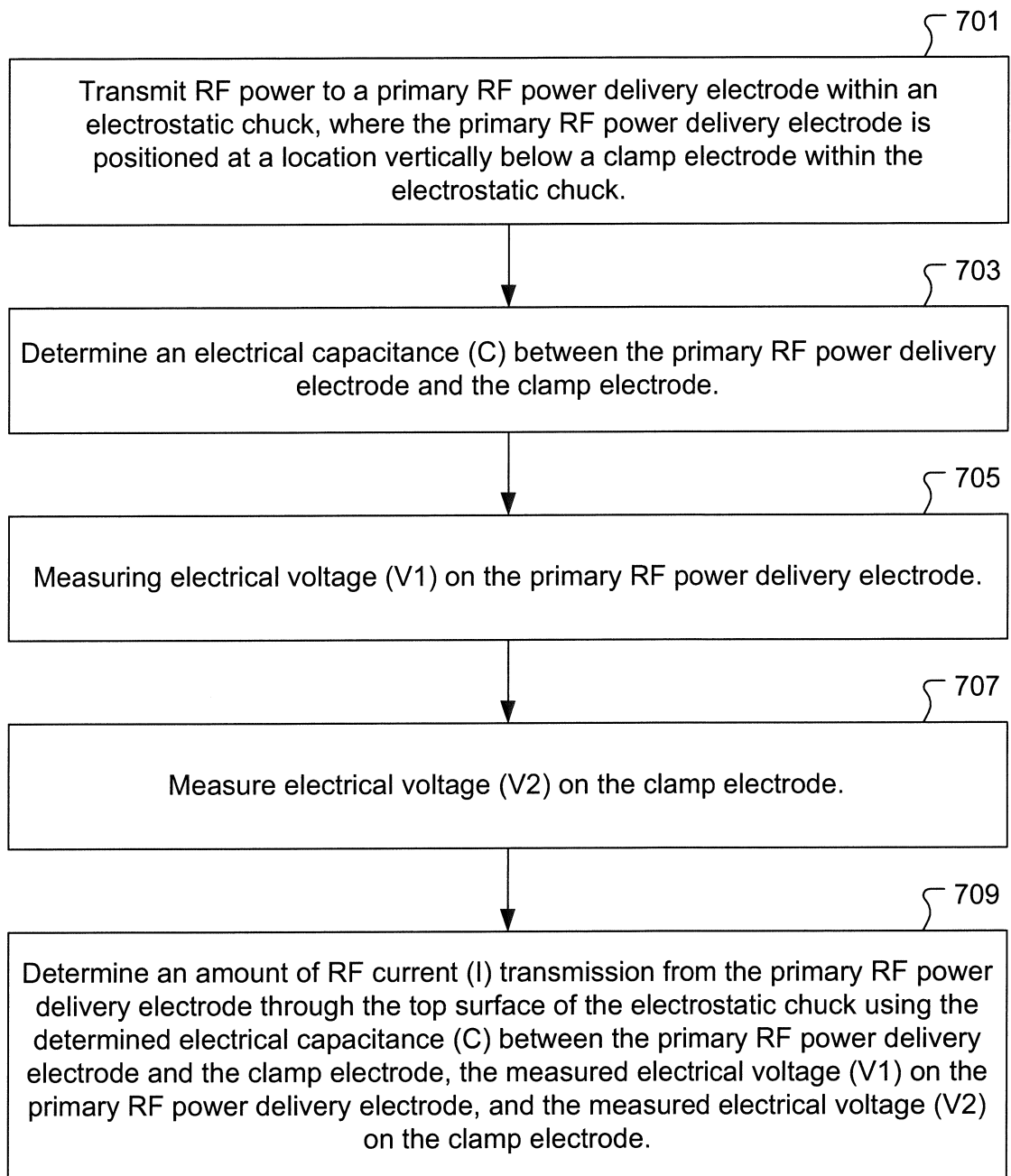


Fig. 7

§ 801

Form ceramic assembly having a top surface including an area configured to support a substrate by:

positioning a clamp electrode within the ceramic assembly in an orientation substantially parallel to the top surface of the ceramic assembly and at an upper location within the ceramic assembly such that a region of the ceramic assembly between the clamp electrode and the top surface of the ceramic assembly is free of other electrically conductive material,

positioning a primary RF power delivery electrode within the ceramic assembly in an orientation substantially parallel to the top surface of the ceramic assembly and at a location vertically below the clamp electrode such that a region of the ceramic assembly between primary RF power delivery electrode and the clamp electrode is free of other electrically conductive material, wherein the primary RF power delivery electrode is configured to extend horizontally through the ceramic assembly to at least span an area underlying the area of the top surface of the ceramic assembly that is configured to support the substrate,

positioning a plurality of RF power delivery connection modules in a substantially uniformly distributed manner about a perimeter of the ceramic assembly, each of the plurality of RF power delivery connection modules configured to form an electrical connection from a lower support structure to the primary RF power delivery electrode at its respective location so as to form an RF power transmission path from the lower support structure to the primary RF power delivery electrode at its respective location.



§ 803

Attach the ceramic assembly to the lower support structure, with the lower support structure formed of an electrically conductive material, and with the lower support structure having a bowl shape formed by a bottom plate member and an annular-shaped wall member extending upward from the bottom plate member, and with the ceramic assembly attached to the lower support structure such that an outer peripheral region of a bottom surface of the ceramic assembly is supported by a top surface of the annular-shaped wall member of the lower support structure with an interior region of the lower support structure exposed to a portion the bottom surface of the ceramic assembly.

Fig. 8